What is claimed is:

1. A high frequency laminated device comprising:

a laminated body including

a first sheet having a relative permeability larger than 1,

a second sheet having a relative permeability larger than 1 on a first surface of said first sheet, and

a third sheet provided over a second surface of said first sheet;

a first inductor pattern forming a first inductor and provided between said first and second sheets; and

first and second capacitor patterns forming a capacitor and opposed to each other about said third sheet therebetween.

2. The high frequency laminated device of claim 1, wherein said third sheet comprises a dielectric sheet.

3. The high frequency laminated device of claim 2, wherein said first and third sheets are stacked and sintered after said first capacitor pattern is printed at an interface between said first and third sheets.

4. The high frequency laminated device of claim 1, further comprising a via-conductor formed in said first sheet, for electrically connecting said first inductor pattern and said first capacitor pattern.

5. The high frequency laminated device of claim 1, further comprising a circuit element mounted on a surface of said laminated body and connected

to at least one of said first inductor and said capacitor.

6. The high frequency laminated device of claim 1, further comprising a second inductor pattern forming a second inductor provided between said first and second sheets.